CONVIDA
WIRELESS

November 15, 2016

To: oneM2M Technical Plenary

Subject: Nomination of candidate to the position of oneM2M Working Group 1 (REQ) Vice-Chair

Convida Wireless is pleased to propose Catalina Mladin as a candidate for the position of Working Group 1 Vice-Chair of the oneM2M Technical Plenary dedicated to Requirements.

Catalina has been actively involved in M2M standardization in such organizations as oneM2M and 3GPP. During her tenure in these organizations, Catalina has made many technical contributions towards the development of these standards.   Catalina also has experience developing M2M and IoT platform solutions based on technologies standardized by these organizations. Based on this experience, Catalina has a deep understanding of the requirements for end-to-end M2M and IoT solutions.

Convida Wireless firmly believes in the need for global M2M standards for the market to realize its full potential, and is fully committed to support Catalina in her role as Working Group 1 Vice-Chair if she is elected.

Sincerely,

James J. Nolan

Manager

Convida Wireless

CATALINA M. MLADIN

Member of Technical Staff, IoT R&D

IoT Research & Development • InterDigital Communications and Convida Wireless
1001 E Hector St Conshohocken, PA 19428 USA • T: +1 610-878-5648 • Catalina.Mladin@ConvidaWireless.com

STANDARDS AND LEADERSHIP EXPERIENCE

2012-Present   oneM2M, Delegate
2009-2012   3GPP RAN3, Delegate
2014-Present   IEEE Women in Engineering (WIE), Philadelphia Chapter Vice-chair

PROFESSIONAL EXPERIENCE

2012-Present • Member of Technical Staff, IoT R&D •
InterDigital Communications and Convida Wireless, Conshohocken, PA, USA
Developing standards and innovation strategies related to M2M/IoT communications, focused on Service Layer aspects.

2009-2012 • Senior Staff Engineer, Standards • InterDigital Communications, King of Prussia, PA, USA
Supported internal research focused on 3GPP network solutions, executed the company standards and innovation strategy for 3G and 4G technologies.

2005-2009 • Senior Staff Engineer, DSP • InterDigital Communications, King of Prussia, PA, USA
Design, development, coding, testing, and integration of embedded firmware. Led technical resources for UMTS and LTE modem development and co-lead a modem integration project.

2001-2005 • Staff Engineer, Software • InterDigital Germany, Munich, Germany
Sole company representative in major 3G development initiative at partner site. Defined business requirements and project scope, milestones, and deliverables. Solution design, development, deployment, and testing. Performed interoperability tests and provided field trial support.

1999-2001 • Senior Engineer, Software • InterDigital Communications, King of Prussia, PA, USA
Analyzed emerging 3G protocols/standards and their interaction through various OSI layers. Designed firmware interfaces and developed application procedures in SDL and C.

1997-1999 • Product Engineer • Drexelbrook Engineering, Horsham, PA, USA
Firmware implementation and product support for ultrasound and radar industrial equipment.

EDUCATION

Masters of Science in Electrical Engineering
Villanova University, Villanova, Pennsylvania

Graduate Certificate in Wireless Communications
Villanova University, Villanova, Pennsylvania

Bachelor of Science in Electrical Engineering
Drexel University, Philadelphia, Pennsylvania *(Magna Cum Laude) ~ 3-time International Honors Award Winner ~ Tau Beta Pi Engineering Honor Society ~ Golden Key National Honor Society ~ Multiple Scholarship Winner*

LANGUAGES

Romanian: native   **English**: fluent   **German, French**: basic